Renesas Electronics America Inc - R5F21388SNFP#30 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	75
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 20x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21388snfp-30

Table 1.7 Pin Name Information by Pin Number (SSU/I²C, Timer RJ, and Timer RB2) (2)

Port	Pin No.	SSU/I²C						Timer RJ		Timer RB2
		SCL_0	SDA_0	SSI_0	$\overline{SCS\_0}$	SSCK_0	SSO_0	TRJO_0	TRJIO_0	TRBO_0
P8_0	44									
P8_1	43									
P8_2	42									
P8_3	41									
P8_4	40									
P8_5	39									
P8_6	38									
P8_7	37									
P9_0	34									
P9_1	33									
P9_2	32									
P9_3	31									
P9_4	79									
P9_5	78									

Table 1.8 Pin Name Information by Pin Number (Timer RC, Timer RE2, and Others) (1)

Port	Pin No.	Timer RC						Timer RE2	Others		
		TRCCLK_0	TRCIOA_0	TRCIOB_0	TRCIOC_0	TRCIOD_0	TRCTRG_0	TMRE2O			
P0_0	72		TRCIOA_0				TRCTRG_0		AN7		
P0_1	71		TRCIOA_0				TRCTRG_0		AN6		
P0_2	70		TRCIOA_0				TRCTRG_0		AN5		
P0_3	69			TRCIOB_0					AN4		
P0_4	68			TRCIOB_0				TMRE2O	AN3		
P0_5	67			TRCIOB_0					AN2		
P0_6	66					TRCIOD_0			AN1		
P0_7	65				TRCIOC_0				AN0		
P1_0	56					TRCIOD_0			AN8	$\overline{KI0}$	
P1_1	55		TRCIOA_0				TRCTRG_0		AN9	$\overline{KI1}$	
P1_2	54			TRCIOB_0					AN10	$\overline{KI2}$	
P1_3	53				TRCIOC_0				AN11	$\overline{KI3}$	
P1_4	52	TRCCLK_0									
P1_5	51										
P1_6	50								IVREF1		CH00
P1_7	49								IVCMP1		CH01
P2_0	30			TRCIOB_0							CH16
P2_1	29				TRCIOC_0						CH17
P2_2	28					TRCIOD_0					CH18
P2_3	27										CH19
P2_4	26										CH20
P2_5	25										CH21
P2_6	24										CH22
P2_7	23										CH23
P3_0	4										CH24
P3_1	36										CH10
P3_2	3										CH25
P3_3	22	TRCCLK_0							IVCMP3		
P3_4	21				TRCIOC_0				IVREF3		
P3_5	20					TRCIOD_0					
P3_6	35										CH11
P3_7	19										
P4_2	5								VREF		
P4_3	7								XCIN		
P4_4	8								XCOUT		
P4_5	48								$\overline{ADTRG}$		CH02
P4_6	12								XIN		
P4_7	10								XOUT		
P5_0	18	TRCCLK_0									
P5_1	17		TRCIOA_0				TRCTRG_0				
P5_2	16			TRCIOB_0							
P5_3	15				TRCIOC_0						
P5_4	14					TRCIOD_0					
P5_5	2										CH26
P5_6	1										CH27
P5_7	80										CH28
P6_0	77							TMRE2O			CH31
P6_1	76										CH32
P6_2	75										CH33
P6_3	74										CH34
P6_4	73										CH35
P6_5	47			TRCIOB_0							CH03
P6_6	46				TRCIOC_0						CH04
P6_7	45					TRCIOD_0					CH05
P7_0	64								AN12		
P7_1	63								AN13		
P7_2	62								AN14		
P7_3	61								AN15		
P7_4	60								AN16		
P7_5	59								AN17		
P7_6	58								AN18		
P7_7	57								AN19		

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts. Interrupts are disabled when the I flag is 0, and are enabled when the I flag is 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is 0. USP is selected when the U flag is 1. The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction for a software interrupt numbered from 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns eight processor interrupt priority levels from 0 to 7. If a requested interrupt has higher priority than IPL, the interrupt is enabled.

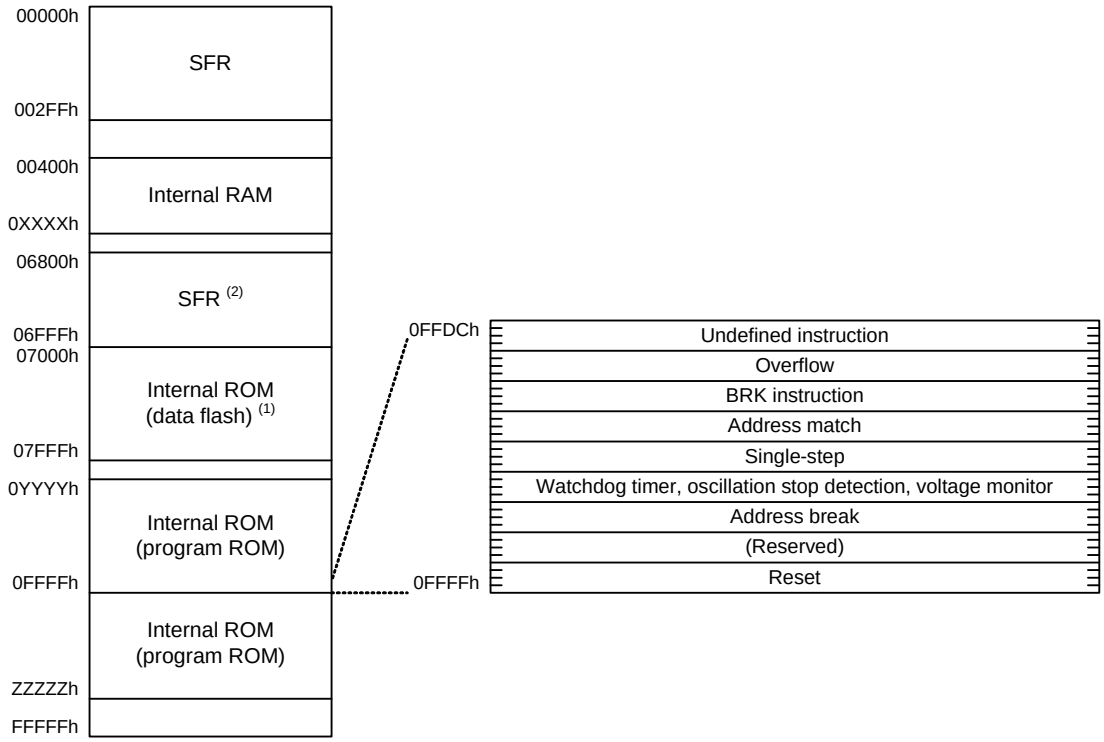
2.8.10 Reserved Bit

The write value must be 0. The read value is undefined.

3. Address Space

3.1 Memory Map

Figure 3.1 shows the Memory Map. The R8C/38T-A Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. Up to 32 Kbytes of the internal ROM (program ROM) is allocated at lower addresses, beginning with address 0FFFFh. The area in excess of 32 Kbytes is allocated at higher addresses, beginning with address 10000h. For example, a 64-Kbyte internal ROM is allocated at addresses 08000h to 17FFFh.
The fixed interrupt vector table is allocated at addresses 0FFDCh to 0FFFFh. The start address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated at addresses 07000h to 07FFFh.
The internal RAM is allocated at higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM is allocated at addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated at addresses 00000h to 02FFFh and addresses 06800h to 06FFFh. Peripheral function control registers are allocated here. All unallocated locations within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Addresses 06800h to 06FFFh are used for the ELC, DTC, and TSCU SFR areas.
3. The blank areas are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F21388SNFP, R5F21388SDFP	64 Kbytes	08000h	17FFFh	6 Kbytes	01BFFh
R5F21388SNFP, R5F21388SDFP	96 Kbytes	08000h	1FFFFh	8 Kbytes	023FFh
R5F21388SNFP, R5F21388SDFP	128 Kbytes	08000h	27FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

Table 3.3 SFR Information (3) (1)

Address	Symbol	Register Name	After Reset	Remarks
0007Ah				
0007Bh				
0007Ch				
0007Dh				
0007Eh				
0007Fh				
00080h	U0MR_0	UART0_0 Transmit/Receive Mode Register	00h	
00081h	U0BRG_0	UART0_0 Bit Rate Register	XXh	
00082h	U0TB_0	UART0_0 Transmit Buffer Register	XXh	
00083h			XXh	
00084h	U0C0_0	UART0_0 Transmit/Receive Control Register 0	00001000b	
00085h	U0C1_0	UART0_0 Transmit/Receive Control Register 1	00000010b	
00086h	U0RB_0	UART0_0 Receive Buffer Register	XXXXh	
00087h				
00088h	U0IR_0	UART0_0 Interrupt Flag and Enable Register	00h	
00089h				
0008Ah				
0008Bh				
0008Ch	LINCR2_0	LIN_0 Special Function Register	00h	
0008Dh				
0008Eh	LINCT_0	LIN_0 Control Register	00h	
0008Fh	LINST_0	LIN_0 Status Register	00h	
00090h	U0MR_1	UART0_1 Transmit/Receive Mode Register	00h	
00091h	U0BRG_1	UART0_1 Bit Rate Register	XXh	
00092h	U0TB_1	UART0_1 Transmit Buffer Register	XXh	
00093h			XXh	
00094h	U0C0_1	UART0_1 Transmit/Receive Control Register 0	00001000b	
00095h	U0C1_1	UART0_1 Transmit/Receive Control Register 1	00000010b	
00096h	U0RB_1	UART0_1 Receive Buffer Register	XXXXh	
00097h				
00098h	U0IR_1	UART0_1 Interrupt Flag and Enable Register	00h	
00099h				
0009Ah				
0009Bh				
0009Ch				
0009Dh				
0009Eh				
0009Fh				
000A0h				
000A1h				
000A2h				
000A3h				
000A4h				
000A5h				
000A8h				
000A9h				
000AAh				
000ABh				
000ACh				
000ADh				
000AEh				
000AFh				
000B0h				
000B1h				
000B4h				
000B5h				
000B8h				
000B9h				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.5 SFR Information (5) (1)

Address	Symbol	Register Name	After Reset	Remarks
000FAh				
000FBh				
000FCh				
000FDh				
000FEh				
000FFh				
00100h				
00101h				
00102h				
00103h				
00104h				
00105h				
00106h				
00107h				
00108h				
00109h				
0010Ah				
0010Bh				
0010Ch				
0010Dh				
0010Eh				
0010Fh				
00110h	TRJ_0	Timer RJ_0 Counter Register	FFFFh	
00111h				
00112h	TRJCR_0	Timer RJ_0 Control Register	00h	
00113h	TRJIOC_0	Timer RJ_0 I/O Control Register	00h	
00114h	TRJMR_0	Timer RJ_0 Mode Register	00h	
00115h	TRJISR_0	Timer RJ_0 Event Pin Select Register	00h	
00116h				
00117h				
00118h				
00119h				
0011Ah				
0011Bh				
0011Ch				
0011Dh				
0011Eh				
0011Fh				
00120h				
00121h				
00122h				
00123h				
00124h				
00125h				
00126h				
00127h				
00128h				
00129h				
0012Ah				
0012Bh				
0012Ch				
0012Dh				
0012Eh				
0012Fh				
00130h	TRBCR_0	Timer RB2_0 Control Register	00h	
00131h	TRBOCR_0	Timer RB2_0 One-Shot Control Register	00h	
00132h	TRBIOC_0	Timer RB2_0 I/O Control Register	00h	
00133h	TRBMR_0	Timer RB2_0 Mode Register	00h	
00134h	TRBPRE_0	Timer RB2_0 Prescaler Register	FFh	
00135h	TRBPR_0	Timer RB2_0 Primary Register	FFh	
00136h	TRBSC_0	Timer RB2_0 Secondary Register	FFh	
00137h	TRBIR_0	Timer RB2_0 Interrupt Request Register	00h	
00138h	TRCCNT_0	Timer RC_0 Counter	0000h	
00139h				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.17 ID code Area, Option Function Select Area

Address	Symbol	Area Name	After Reset	Address size
:				
0FFDBh	OFS2	Option Function Select Register 2	(Note 1)	
:				
0FFDFh	ID1		(Note 2)	
:				
0FFE3h	ID2		(Note 2)	
:				
0FFEBh	ID3		(Note 2)	
:				
0FFEFh	ID4		(Note 2)	
:				
0FFF3h	ID5		(Note 2)	
:				
0FFF7h	ID6		(Note 2)	
:				
0FFFBh	ID7		(Note 2)	
:				
0FFFFh	OFS	Option Function Select Register	(Note 1)	

Notes:
1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not perform any additional writes to the option function select area. Erasing the block including the option function select area sets the option function select area to FFh.
2. The ID code area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not perform any additional writes to the ID code area. Erasing the block including the ID code area sets the ID code area to FFh.

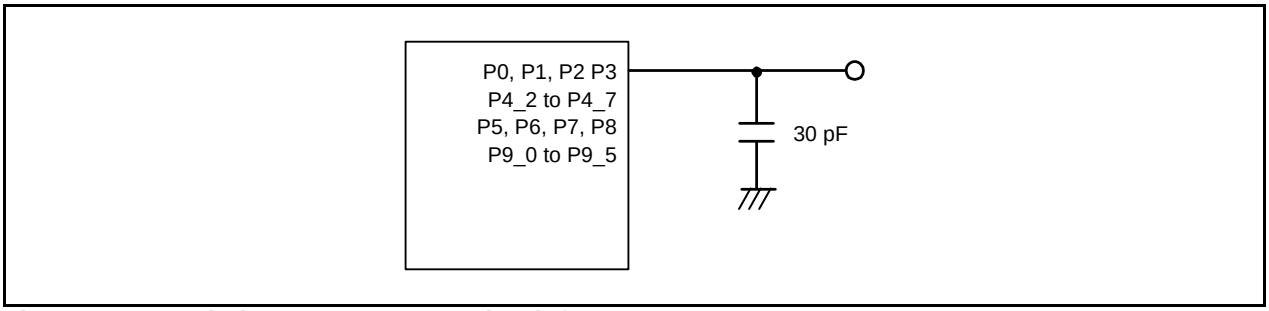


Figure 4.1 Timing Measurement Circuit for Ports P0, P1, P2, P3, P4_2 to P4_7, P5, P6, P7, P8, and P9_0 to P9_5

Table 4.5 Flash Memory (Program ROM) Characteristics (Vcc = 2.7 V to 5.5 V, Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

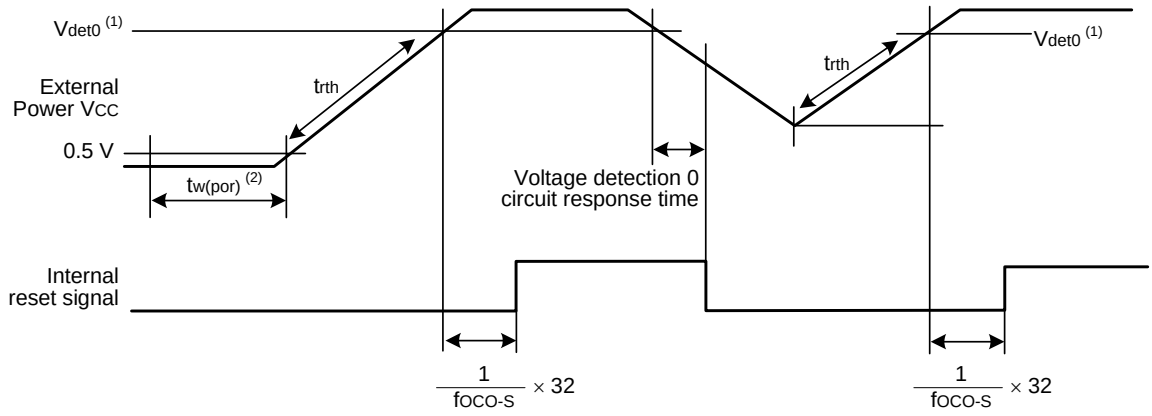
Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		1,000 (2)	—	—	times
—	Byte program time (Program and erase endurance ≤ 100 times)		—	—	—	µs
—	Byte program time (Program and erase endurance ≤ 1,000 times)		—	—	—	µs
—	Word program time (Program and erase endurance ≤ 100 times)	Topr = 25°C, Vcc = 5.0 V	—	100	200	µs
—	Word program time (Program and erase endurance ≤ 100 times)		—	100	400	µs
—	Word program time (Program and erase endurance ≤ 1,000 times)		—	100	650	µs
—	Block erase time		—	0.3	4	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		–20 (N ver.) –40 (D ver.)	—	85	°C
—	Data hold time (6)	Ambient temperature = 55°C (7)	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 100 or 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. The data hold time includes 7,000 hours under an environment of ambient temperature 85°C.

Table 4.10 Power-On Reset Circuit Characteristics (1)
(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{rth}	External power VCC rise gradient		0	—	50,000	mV/msec

Note:
1. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.



Notes:
1. V_{det0} indicates the voltage detection level of the voltage detection 0 circuit. Refer to the **Voltage Detection Circuit** chapter of User's Manual: Hardware for details.
2. $t_{w(por)}$ indicates the duration the external power Vcc must be held below the valid voltage (0.5 V) to enable a power-on reset. When turning on the power after it falls with voltage monitor 0 reset disabled, maintain $t_{w(por)}$ for 1 ms or more.

Figure 4.3 Power-on Reset Circuit Characteristics

Table 4.11 High-Speed On-Chip Oscillator Circuit Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	High-speed on-chip oscillator frequency after reset	Vcc = 1.8 V to 5.5 V, –20°C ≤ Topr ≤ 85°C (N version) –40°C ≤ Topr ≤ 85°C (D version)	—	40	—	MHz
	High-speed on-chip oscillator frequency when 01b or 10b is written to bits FRA25 and FRA24 in the FRA2 register (1)		—	36.864	—	MHz
	High-speed on-chip oscillator frequency when 10b is written to bits FRA25 and FRA24 in the FRA2 register		—	32	—	MHz
	High-speed on-chip oscillator frequency dependence on temperature and power supply voltage (2)		– 1.5	—	1.5	%
—	Oscillation stability time	Vcc = 5.0 V, Topr = 25°C	—	250	—	µs
—	Self power consumption at oscillation	Vcc = 5.0 V, Topr = 25°C	—	500	—	µA

Notes:
1. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.
2. This indicates the precision error for the oscillation frequency of the high-speed on-chip oscillator.

Table 4.15 DC Characteristics (2) [3.3 V ≤ Vcc ≤ 5.5 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	6.5	15	mA
			16 MHz	Off	Off	125 kHz	No division	—		—	5.3	12.5	mA
			10 MHz	Off	Off	125 kHz	No division	—		—	3.6	—	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	3.0	—	mA
			16 MHz	Off	Off	125 kHz	Divide-by-8	—		—	2.2	—	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz (3)	125 kHz	No division	—		—	7.0	15	mA
			Off	Off	20 MHz (3)	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	400	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	—	FMR27 = 1 SVC0 = 0		—	85	400	µA
			Off	32 kHz	Off	Off	—	FMSTP = 1 SVC0 = 0	Program operation on RAM Flash memory off	—	47	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	100	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	90	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 3.3 V to 5.5 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Table 4.19 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V] (Topr = –20°C to 85°C (N version)/–40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—		—	2.2	—	mA
			5 MHz	Off	Off	125 kHz	Divide-by-8	—		—	0.8	—	mA
		High-speed on-chip oscillator mode	Off	Off	5 MHz (3)	125 kHz	No division	—		—	2.5	10	mA
			Off	Off	5 MHz (3)	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	300	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0		—	80	350	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	µA

Notes:
1. Vcc = 1.8 V to 2.7 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

4.5 AC Characteristics

Table 4.20 Timing Requirements of Clock Synchronous Serial I/O with Chip Select (during Master Operation) (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time		4.00	—	—	t_{CYC} (1)
t_{HI}	SSCK clock high width		0.40	—	0.60	t_{SUCYC}
t_{LO}	SSCK clock low width		0.40	—	0.60	t_{SUCYC}
t_{RISE}	SSCK clock rising time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	0.50	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)
t_{FALL}	SSCK clock falling time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	0.50	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)
t_{SU}	SSI, SSO data input setup time	4.5 V ≤ Vcc ≤ 5.5 V	60	—	—	ns
		2.7 V ≤ Vcc < 4.5 V	70	—	—	ns
		1.8 V ≤ Vcc < 2.7 V	100	—	—	ns
t_H	SSI, SSO data input hold time	2.7 V ≤ Vcc ≤ 5.5 V	2.00	—	—	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	2.00	—	—	t_{CYC} (1)
t_{LEAD}	$\overline{SCS}$-SCK output delay time		0.5 t_{SUCYC} - 1 t_{CYC}	—	—	ns
t_{LAG}	SCK -$\overline{SCS}$ output valid time		0.5 t_{SUCYC} - 1 t_{CYC}	—	—	ns
t_{OD}	SSO data output delay time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	30.00	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)

Note:
1. 1t_{CYC} = 1/f1 (s)

Table 4.21 Timing Requirements of Clock Synchronous Serial I/O with Chip Select (during Slave Operation) (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time		4.00	—	—	t_{CYC} (1)
t_{HI}	SSCK clock high width		0.40	—	0.60	t_{SUCYC}
t_{LO}	SSCK clock low width		0.40	—	0.60	t_{SUCYC}
t_{RISE}	SSCK clock rising time		—	—	1.00	µs
t_{FALL}	SSCK clock falling time		—	—	1.00	µs
t_{SU}	SSO data input setup time		10.00	—	—	ns
t_{H}	SSO data input hold time		2.00	—	—	t_{CYC} (1)
t_{LEAD}	$\overline{SCS}$ setup time		1t_{CYC} + 50	—	—	ns
t_{LAG}	$\overline{SCS}$ hold time		1t_{CYC} + 50	—	—	ns
t_{OD}	SSI, SSO data output delay time	4.5 V ≤ Vcc ≤ 5.5 V	—	—	60	ns
		2.7 V ≤ Vcc < 4.5 V	—	—	70	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	100.00	ns
t_{SA}	SSI slave access time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	1.5t_{CYC} + 100	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	1.5t_{CYC} + 200	ns
t_{OR}	SSI slave out open time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	1.5t_{CYC} + 100	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	1.5t_{CYC} + 200	ns

Note:
1. 1t_{CYC} = 1/f1 (s)

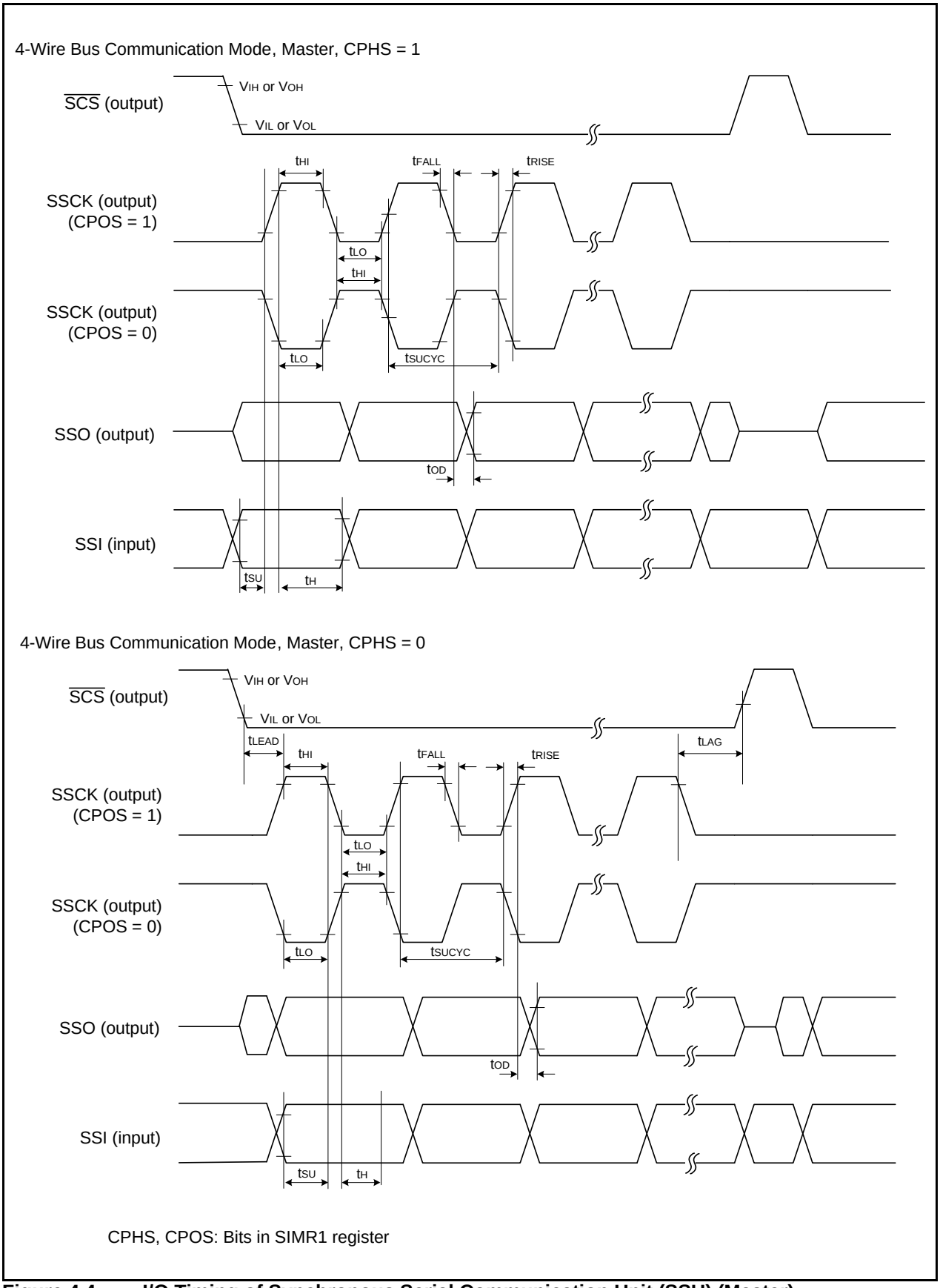


Figure 4.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

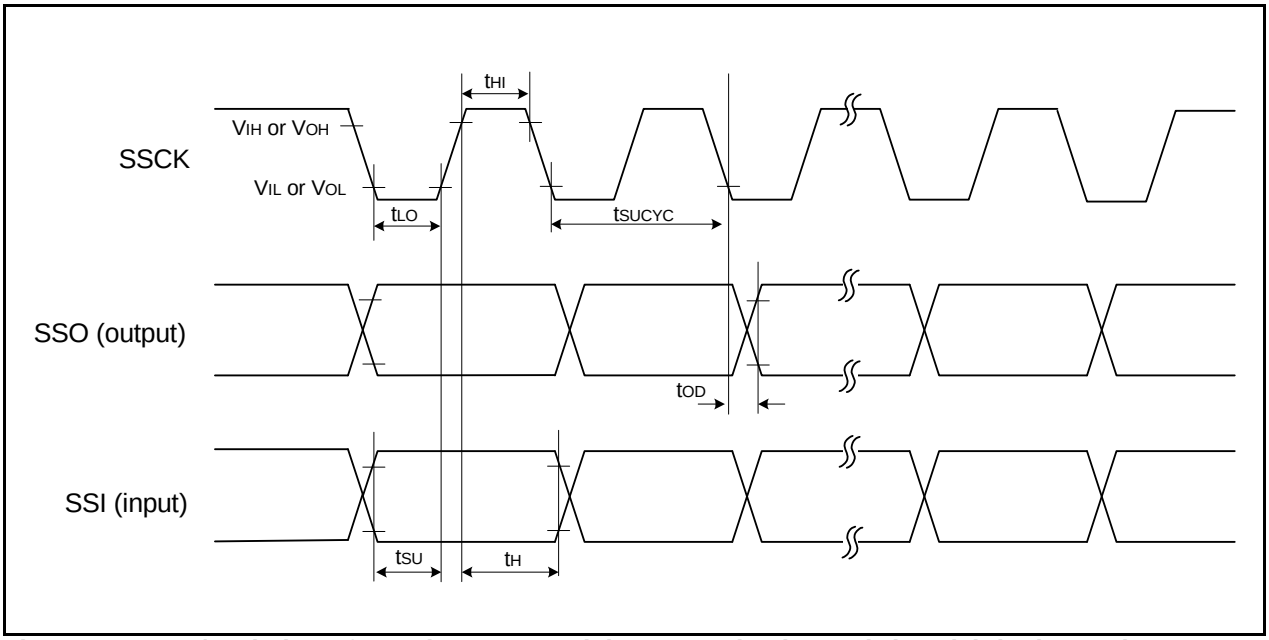


Figure 4.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

Table 4.22 External Clock Input (XOUT, XCIN)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	—	50	—	50	—	ns
$t_{WH(XOUT)}$	XOUT input high width	90	—	24	—	24	—	ns
$t_{WL(XOUT)}$	XOUT input low width	90	—	24	—	24	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	14	—	14	—	µs
$t_{WH(XCIN)}$	XCIN input high width	7	—	7	—	7	—	µs
$t_{WL(XCIN)}$	XCIN input low width	7	—	7	—	7	—	µs

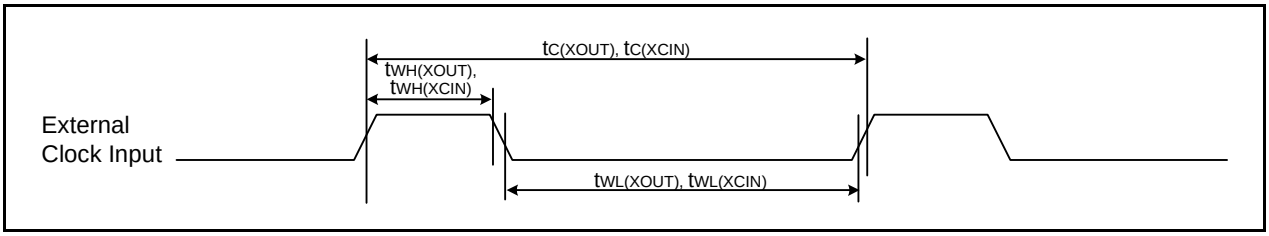


Figure 4.7 External Clock Input Timing Diagram

Table 4.23 Timing Requirements of TRJIO

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(TRJIO)}$	TRJIO input cycle time	500	—	300	—	100	—	ns
$t_{WH(TRJIO)}$	TRJIO input high width	200	—	120	—	40	—	ns
$t_{WL(TRJIO)}$	TRJIO input low width	200	—	120	—	40	—	ns

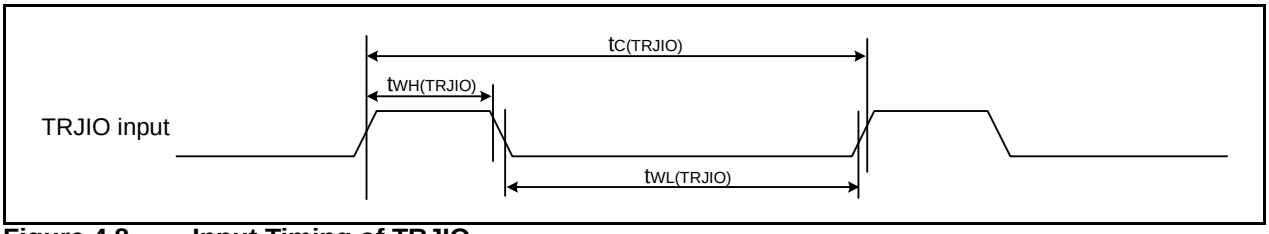


Figure 4.8 Input Timing of TRJIO

Table 4.24 Timing Requirements of Serial Interface (Internal clock selected as transfer clock (master communication))

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{d(C-Q)}$	TXDi output delay time	—	200	—	30	—	10	ns
$t_{su(D-C)}$	RXDi input setup time (1)	150	—	120	—	90	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	90	—	90	—	ns

i = 0 or 1

Note:

1. External pin load condition CL = 30 pF

Table 4.25 Timing Requirements of Serial Interface (External clock selected as transfer clock (slave communication))

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	300	—	200	—	ns
$t_{w(CKH)}$	CLKi input high width	400	—	150	—	100	—	ns
$t_{w(CKL)}$	CLKi input low width	400	—	150	—	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	—	120	—	90	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	30	—	10	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	90	—	90	—	ns

i = 0 or 1

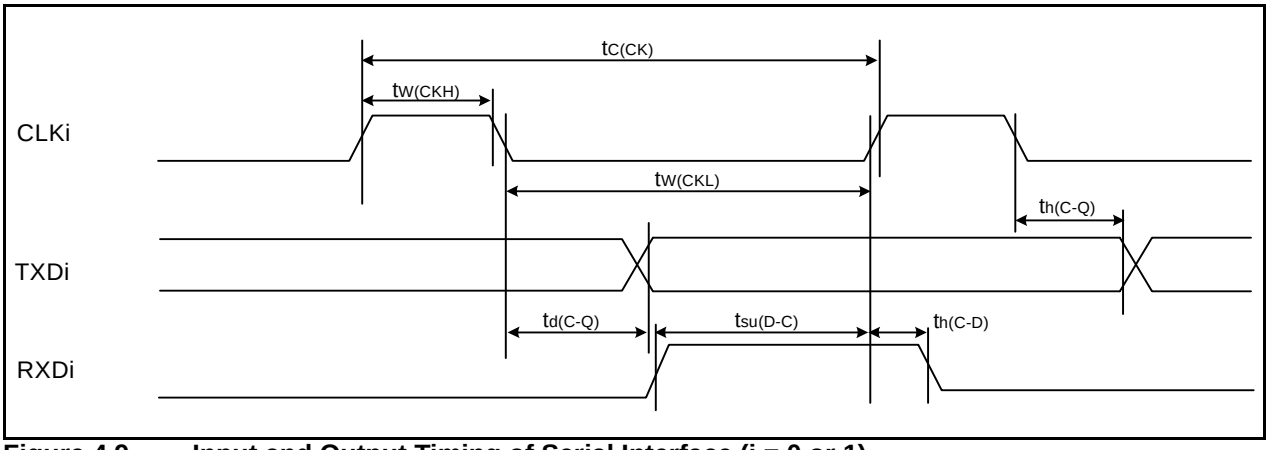


Figure 4.9 Input and Output Timing of Serial Interface (i = 0 or 1)

REVISION HISTORY	R8C/38T-A Group User's Manual: Datasheet

Rev.	Date	Description	
		Page	Summary
0.01	Feb 23, 2011	—	First Edition issued
1.00	Dec 09, 2011	All pages	"Preliminary", "Under development" deleted, "sensor control unit" → "touch sensor control unit"
		2, 3	Tables 1.1 and 1.2 revised
		6	Figure 1.3 revised
		16	2.1 revised
		19, 20, 22 to 25, 27 to31	Tables 3.1, 3.2, 3.4 to 3.7, 3.9 to 3.13
		35	Table 3.17 revised, Note 2 added
		36 to 59	"4. Electrical Characteristics" added

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